Product / Package Information

Package	LFCSP - Punched
Body Size (mm)	10 X 10 X 0.85 (7.16 EP)
LeadCount	84
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
JIG Material Content Compliant	Level A Compliant

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	8.68E-02	86.91	869100	31.80	318011
Thermosets	Epoxy & Phenol Resin	Proprietary	1.28E-02	12.78	127800	4.68	46763
Other inorganic materials	Carbon black	1333-86-4	3.10E-04	0.31	3100	0.11	1134
Subtotal			9.99 E-02	100.00	1000000	36.59	365908

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.37 E-01	96.37	963700	50.20	502031
Copper & its alloys	Nickel	7440-02-0	3.55 E-03	2.50	25000	1.30	13024
Copper & its alloys	Silicon	7440-21-3	8.53 E-04	0.60	6000	0.31	3126
Copper & its alloys	Zinc	7440-66-7	7.11 E-04	0.50	5000	0.26	2605
Copper & its alloys	Silver	7440-22-4	4.27 E-05	0.03	300	0.02	156
Subtotal			1.42 E-01	100.00	1000000	52.09	520941

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	6.30 E-04	100.0	1000000	0.23	2308

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	5.60 E-04	100.0	1000000	0.21	2052

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.52 E-03	100.0	1000000	1.29	12898

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.50 E-02	100.0	1000000	9.15	91459

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Thermoset	Epoxy Resin	Proprietary	7.99 E-04	66.00	660000	0.29	2926
Others	Polymeric Resin	Proprietary	4.11 E-04	34.00	340000	0.15	1507
Subtotal			1.21 E-03	100.0	1000000	0.44	4434

	Weight (g)	Percentage (%)	PPM
Package Totals	**2.73 E-01**	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES